Docket No.: M077P1

APPLICATION DATA SHEET (37 C.F.R. 1.76)

2	INVENTOR & RESIDENCE:	Martin Alter, Los Altos, California
3		Robert Rumsey, Saratoga, California
4	CORRESPONDENCE ADDRESS	S: Eugene H. Valet
5		ValetPatents
6		314 10 th Ave. South
7		Edmonds WA 98020
8		425-672-3147 ff fax 640-0525
9	TITLE:	Integrating Chip Scale Packaging Metallization Into
10		Integrated Circuit Die Structures
11	DRAWING SHEETS:	4
12	SUGGESTED PUBL. FIG. NO.:	3A
13	DOCKET NO:	M-077P1
14	TYPE:	UTILITY
15	ATTORNEY, REG. NO.:	J. Vincent Tortolano, Reg. No. 31,433
16		Eugene H. Valet, 31,435
17	PRIORITY INFORMATION:	Continuation-In-Part of Ser. No. 10/453,157
18	ASSIGNEE:	Micrel, Incorporated, San Jose, California